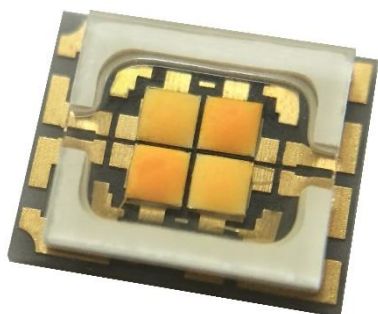




ProLight PBED-10FQE-WVWVR95
10W Power LED
Technical Datasheet
Version: 1.2

ProLight Opto ProEngine Series

Features

- Compact light source
- High R9 color rendering value
- High Color rendering index
- Lead free reflow soldering
- Superior ESD protection
- RoHS compliant

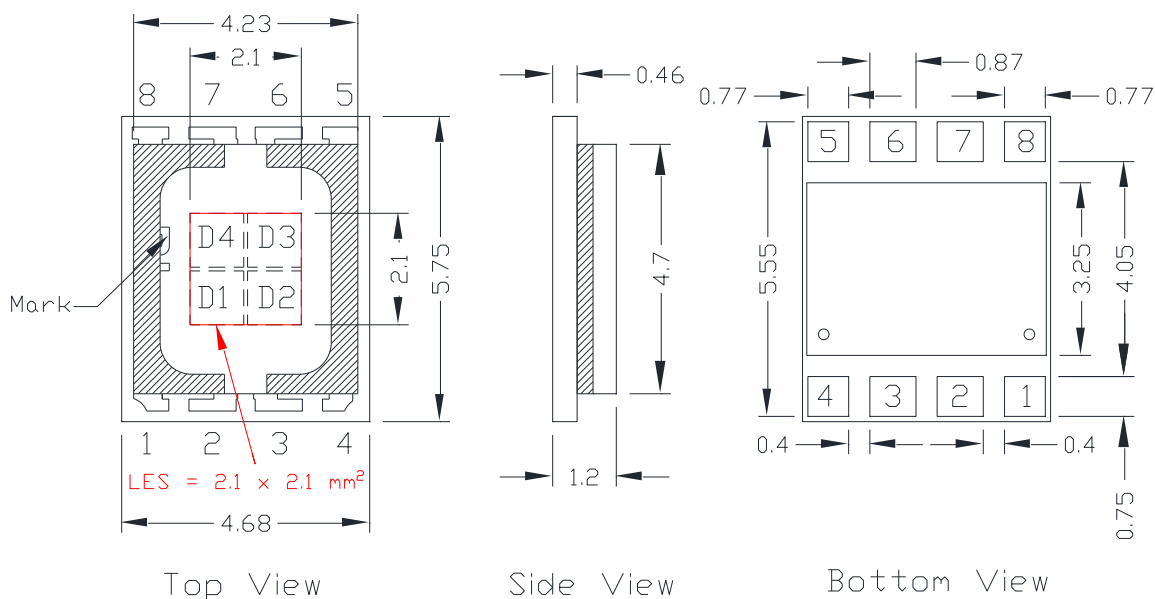
Main Applications

- Surgical lighting
- Entertainment lighting (Stage lighting)
- Architectural lighting
- Mood lighting
- Outdoor lighting
- Indoor lighting

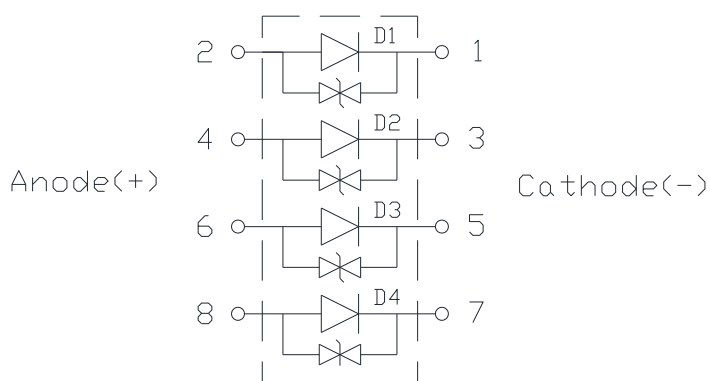
Introduction

- ProLight PBED colorful series is a color changeable LED with maximum 4 color chips in one package. Compared to discrete LEDs, PBED series reduce the distance between LED die, creating a small optical source for excellent optical control and efficient color mixing. ProLight PBED series is much suitable for the application of color-changing lighting, especially for entertainment lighting.

Emitter Mechanical Dimensions



Circuit Diagram



Color

D1 : White
D2 : Warm White
D3 : White
D4 : Warm White

Notes:

1. Drawing not to scale.
2. All dimensions are in millimeters.
3. Unless otherwise indicated, tolerances are $\pm 0.15\text{mm}$.
4. Please do not solder the emitter by manual hand soldering, otherwise it will damage the emitter.
5. Please do not use a force of over 1kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

*The appearance and specifications of the product may be modified for improvement without notice.

Flux Characteristics, $T_j = 25^\circ\text{C}$

Color	Part Number Emitter	Luminous Flux Φ_v (lm)		Refer @350mA Typ.	CRI Typ.	R9 Min.
		@700mA Min.	@700mA Typ.			
D1	White	120	160	85	95	80
D2	Warm White	90	117	60		
D3	White	120	160	85		
D4	Warm White	90	117	60		

- ProLight maintains a tolerance of $\pm 7\%$ on flux and power measurements.
- ProLight maintains a tolerance of ± 3 on R9 measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics, $T_j = 25^\circ\text{C}$

Color	Min.	Forward Voltage V_F (V)		Refer @350mA Typ.
		@700mA Typ.	Max.	
D1	White	2.8	3.1	3.8
D2	Warm White	2.8	3.1	3.8
D3	White	2.8	3.1	3.8
D4	Warm White	2.8	3.1	3.8

- ProLight maintains a tolerance of $\pm 0.5\text{V}$ for Voltage measurements.

Optical Characteristics at 700mA, $T_j = 25^\circ\text{C}$

Radiation Pattern	Color	Color Temperature CCT			Total included Angle (degrees)	Viewing Angle (degrees)
		Min.	Typ.	Max.	$\theta_{0.90v}$	$2\theta_{1/2}$
Lambertian	White	4780 K	5180 K	5580 K	160	120
	Warm White	2790 K	2910 K	3030 K	160	120

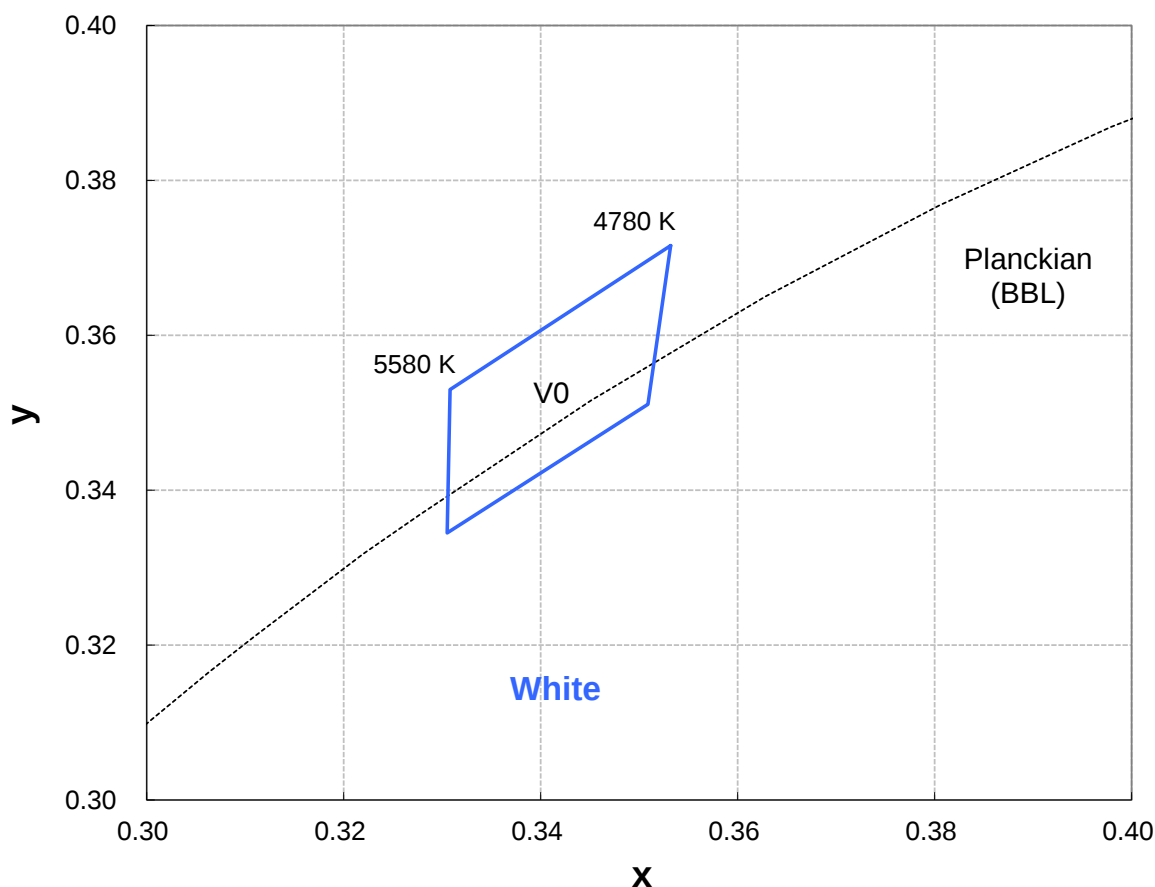
- ProLight maintains a tolerance of $\pm 5\%$ for CCT measurements.

Absolute Maximum Ratings

Parameter	White/Warm White
DC Forward Current (mA)	700
Peak Pulsed Forward Current (mA)	1500 (less than 1/10 duty cycle@1KHz)
ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7)	±4000V (Class III)
LED Junction Temperature	135°C
Operating Board Temperature at Maximum DC Forward Current	-40°C - 85°C
Storage Temperature	-40°C - 120°C
Soldering Temperature	JEDEC 020c 260°C
Allowable Reflow Cycles	3
Reverse Voltage	Not designed to be driven in reverse bias

Color Bin

White Binning Structure Graphical Representation



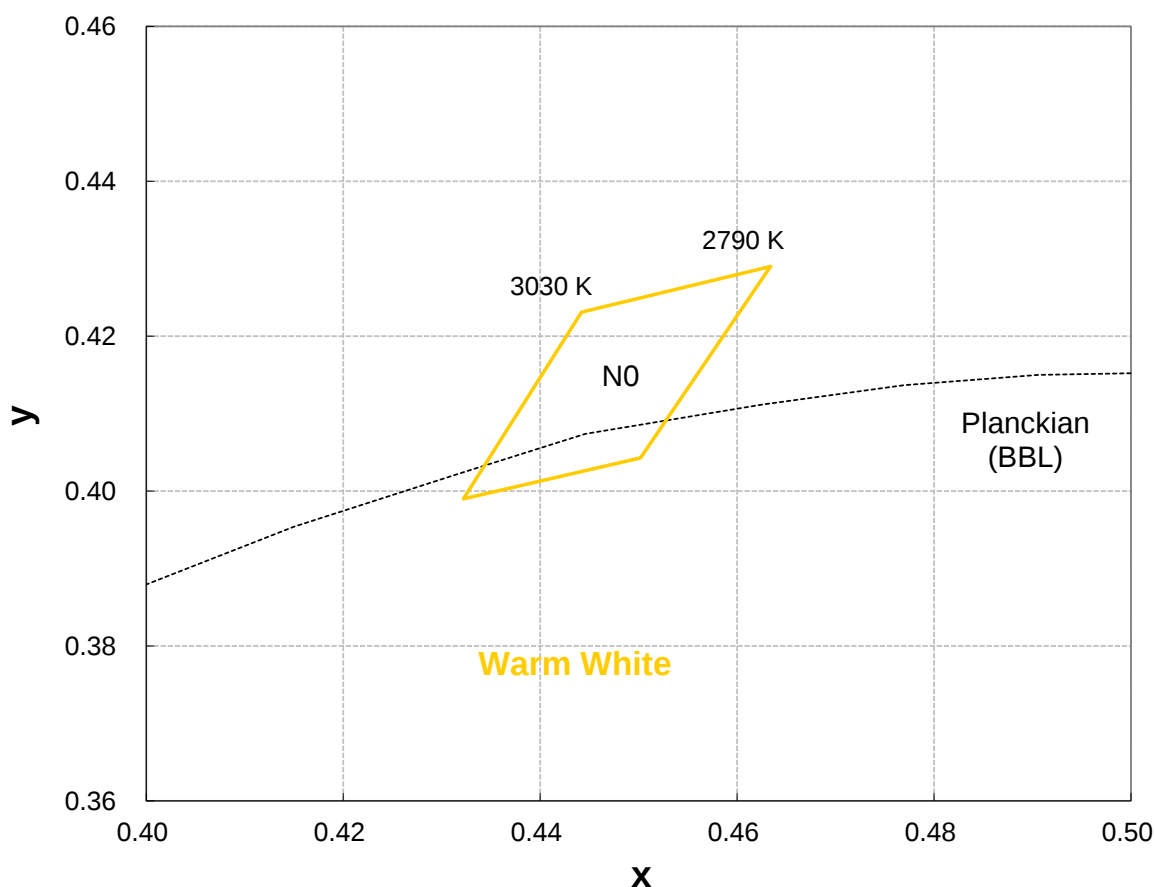
White Bin Structure

Bin Code	x	y	Typ. CCT (K)
V0	0.3532	0.3716	5180
	0.3308	0.3530	
	0.3305	0.3345	
	0.3509	0.3511	

- Tolerance on each color bin (x , y) is ± 0.005

Color Bin

Warm White Binning Structure Graphical Representation



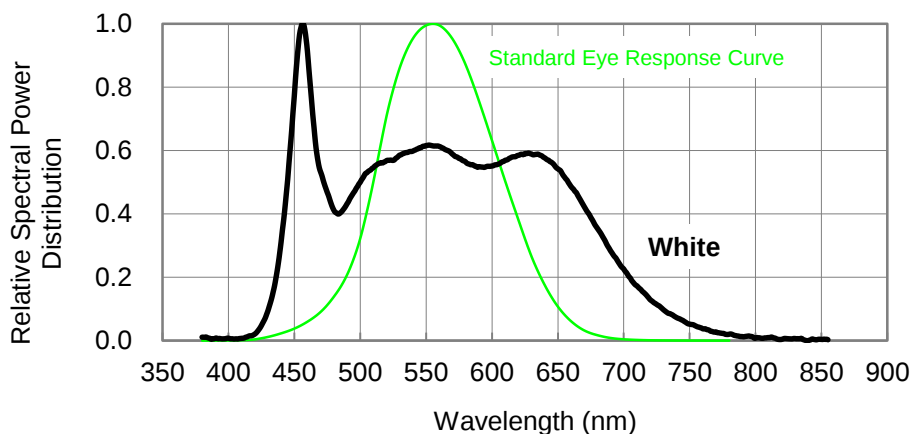
Warm White Bin Structure

Bin Code	x	y	Typ. CCT (K)
N0	0.4634	0.4290	2910
	0.4442	0.4231	
	0.4322	0.3990	
	0.4502	0.4043	

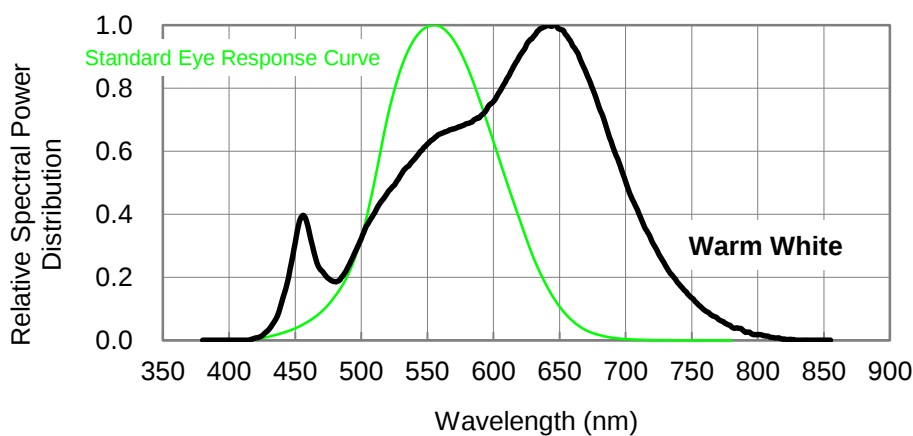
- Tolerance on each color bin (x , y) is ± 0.005

Color Spectrum, $T_j = 25^\circ\text{C}$

1. White

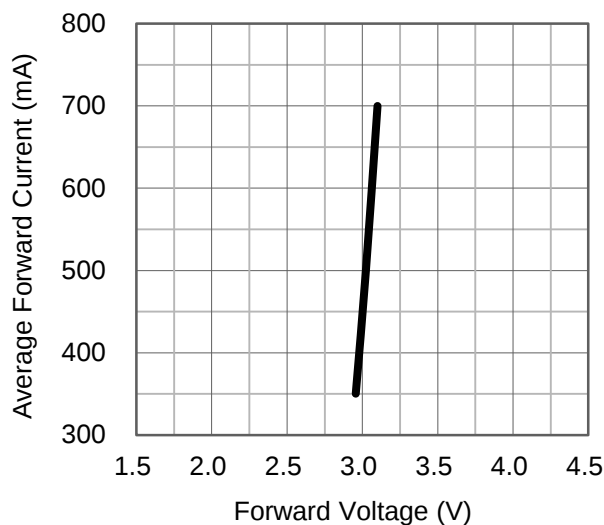


2. Warm White

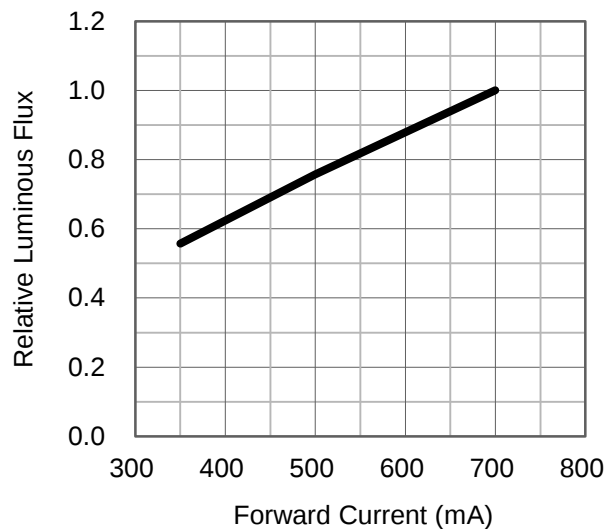


Forward Current Characteristics, $T_j = 25^\circ\text{C}$

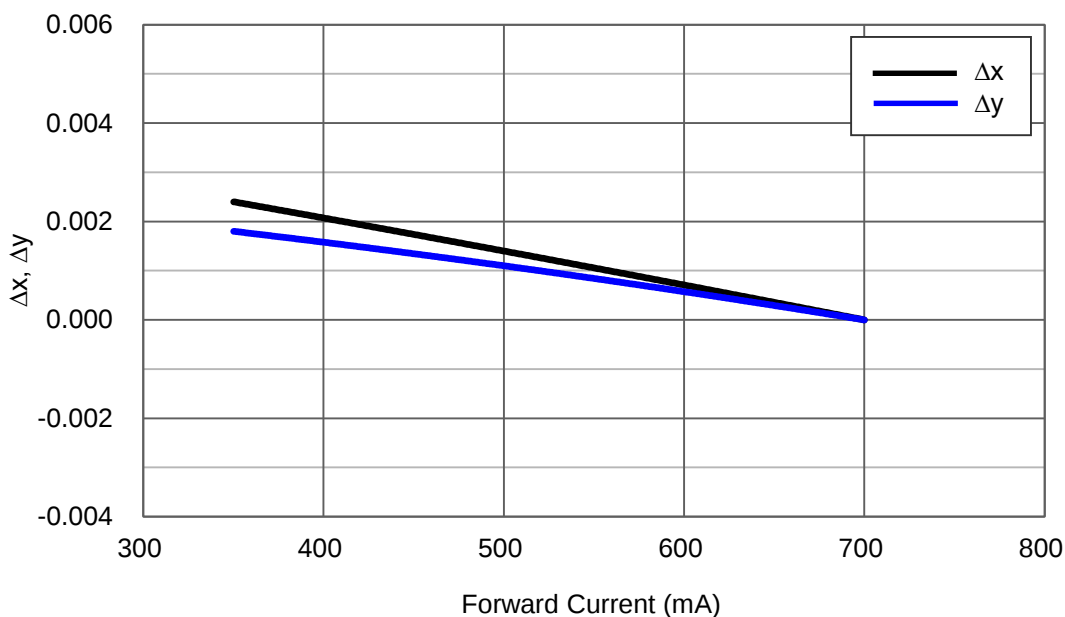
1. Forward Voltage vs. Forward Current



2. Forward Current vs. Normalized Relative Luminous Flux

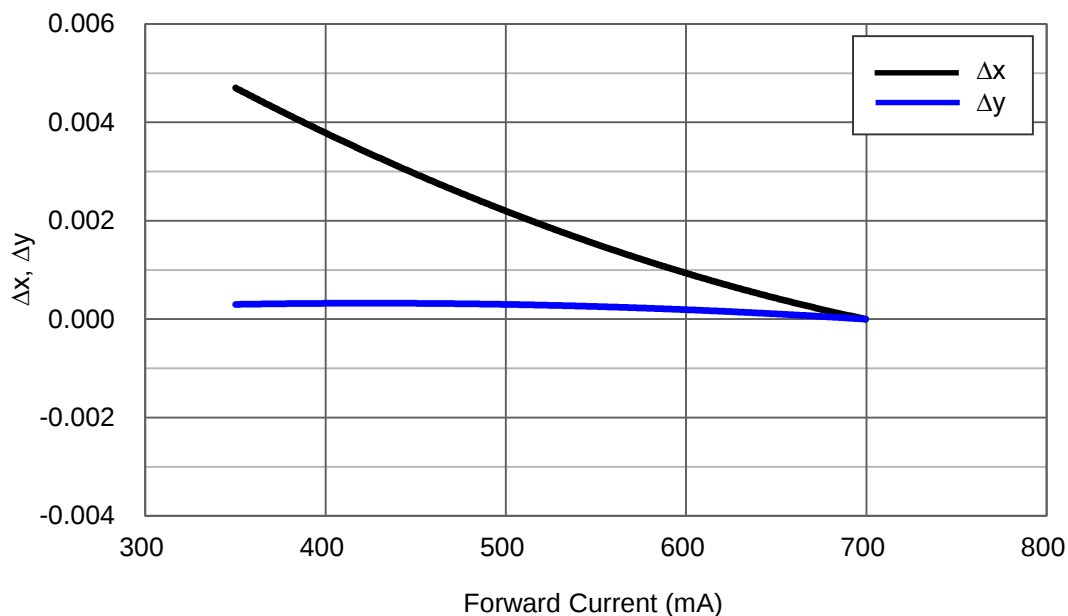


3. White Forward Current vs. Chromaticity Coordinate Shift



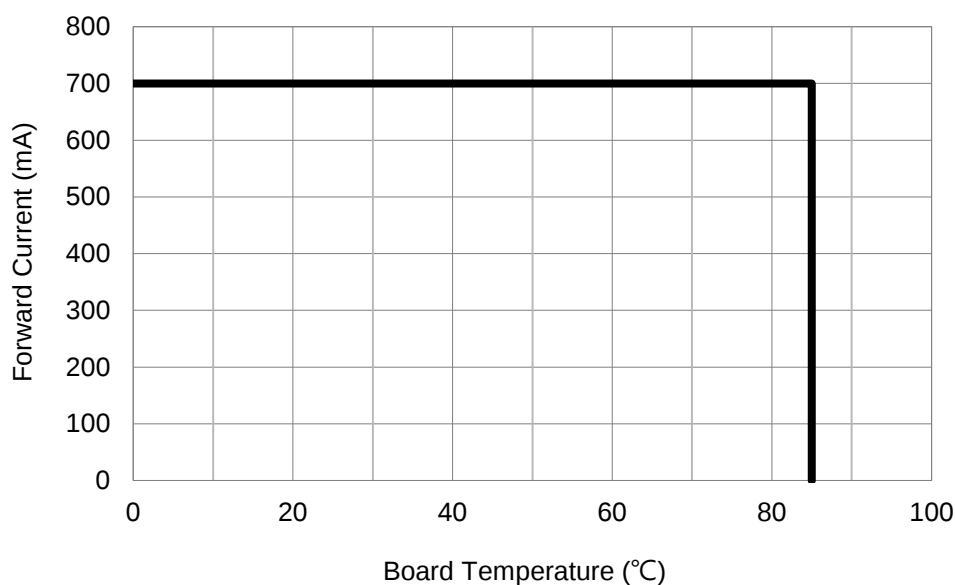
Forward Current Characteristics, $T_j = 25^\circ\text{C}$

4. Warm White Forward Current vs. Chromaticity Coordinate Shift

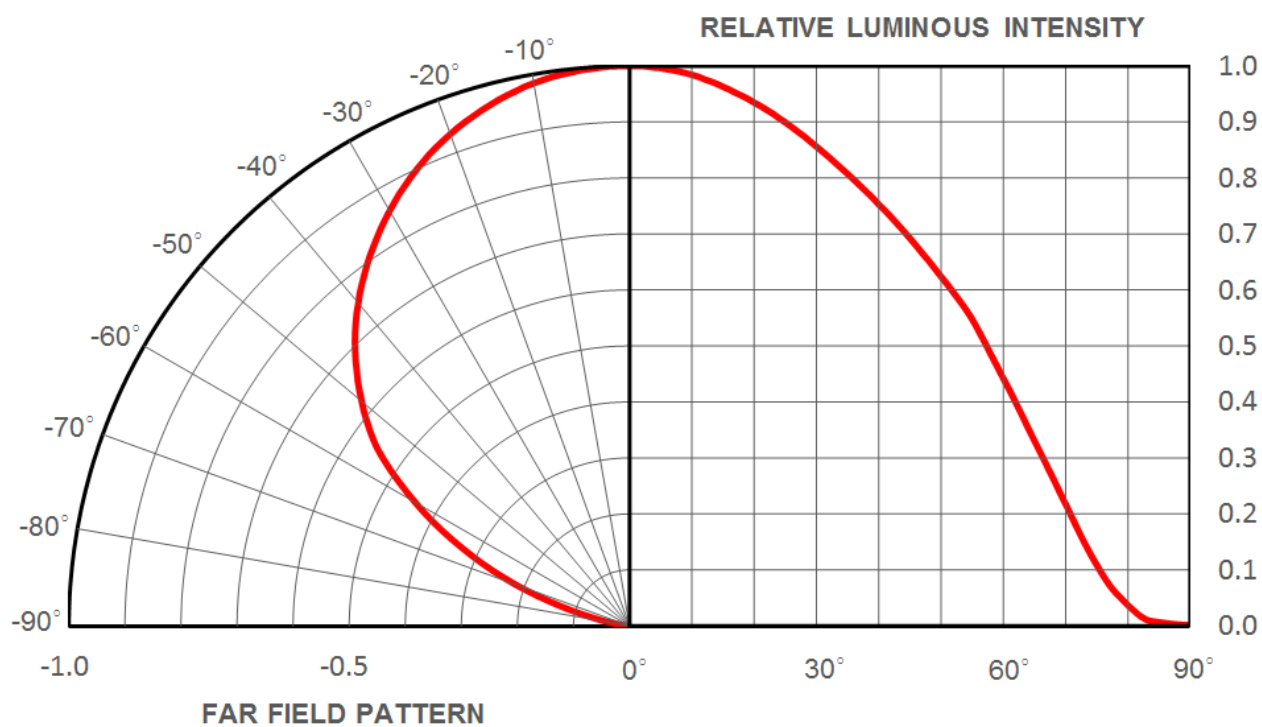


Board Temperature vs. Maximum Forward Current

Maximum Forward Current for 4 chip operated



Typical Representative Spatial Radiation Pattern



Moisture Sensitivity Level - JEDEC Level 1

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	$\leq 30^{\circ}\text{C}$ / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA

- The standard soak time includes a default value of 24 hours for semiconductor manufacture's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

Level	Floor Life		Soak Requirements			
			Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	$\leq 30^{\circ}\text{C}$ / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA
2	1 year	$\leq 30^{\circ}\text{C}$ / 60% RH	168 +5/-0	85°C / 60% RH	NA	NA
2a	4 weeks	$\leq 30^{\circ}\text{C}$ / 60% RH	696 +5/-0	30°C / 60% RH	120 +1/-0	60°C / 60% RH
3	168 hours	$\leq 30^{\circ}\text{C}$ / 60% RH	192 +5/-0	30°C / 60% RH	40 +1/-0	60°C / 60% RH
4	72 hours	$\leq 30^{\circ}\text{C}$ / 60% RH	96 +2/-0	30°C / 60% RH	20 +0.5/-0	60°C / 60% RH
5	48 hours	$\leq 30^{\circ}\text{C}$ / 60% RH	72 +2/-0	30°C / 60% RH	15 +0.5/-0	60°C / 60% RH
5a	24 hours	$\leq 30^{\circ}\text{C}$ / 60% RH	48 +2/-0	30°C / 60% RH	10 +0.5/-0	60°C / 60% RH
6	Time on Label (TOL)	$\leq 30^{\circ}\text{C}$ / 60% RH	Time on Label (TOL)	30°C / 60% RH	NA	NA

Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, $I_F = \text{max DC}$ (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solder Heat Resistance (SHR)	260°C $\pm$ 5°C, 10 sec.		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:

1. Depending on the maximum derating curve.
2. Criteria for judging failure

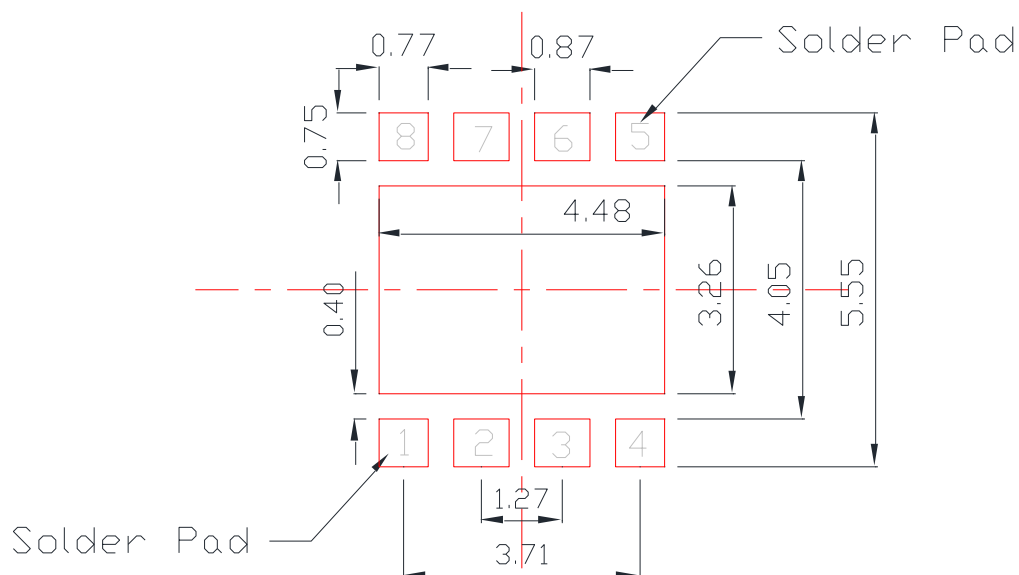
Item	Test Condition	Criteria for Judgement	
		Min.	Max.
Forward Voltage (V_F)	$I_F = \text{max DC}$	--	Initial Level x 1.1
Luminous Flux or Radiometric Power (Φ_V)	$I_F = \text{max DC}$	Initial Level x 0.7	--
Reverse Current (I_R)	$V_R = 5V$	--	50 μA

* The test is performed after the LED is cooled down to the room temperature.

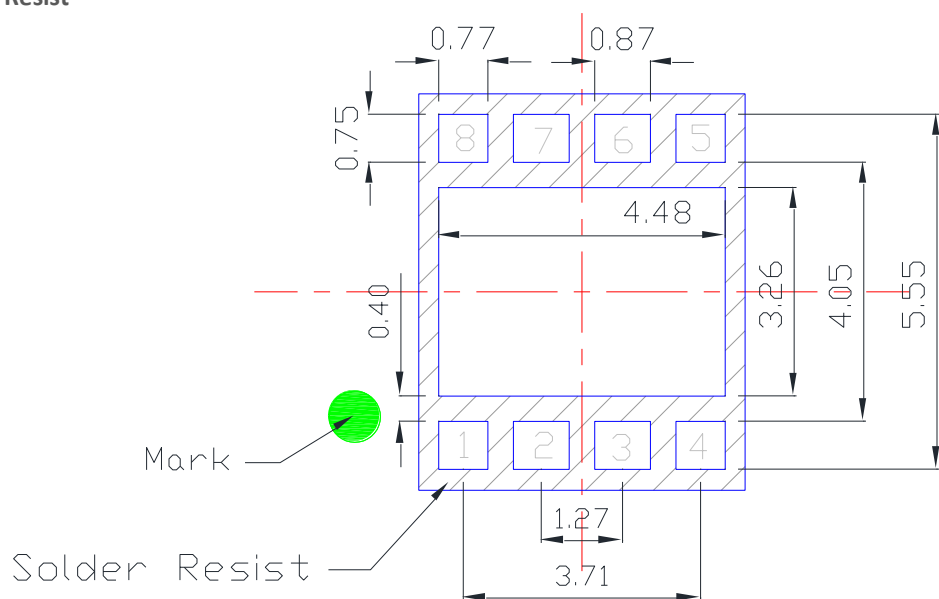
3. A failure is an LED that is open or shorted.

Recommended Solder Pad Design

Solder Pad



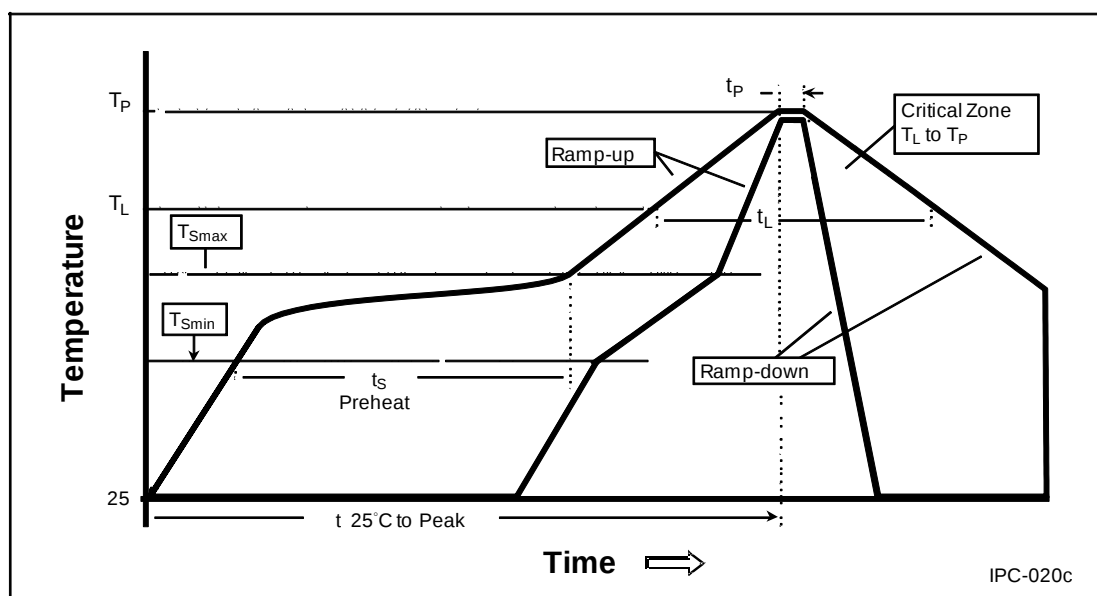
Solder Resist



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

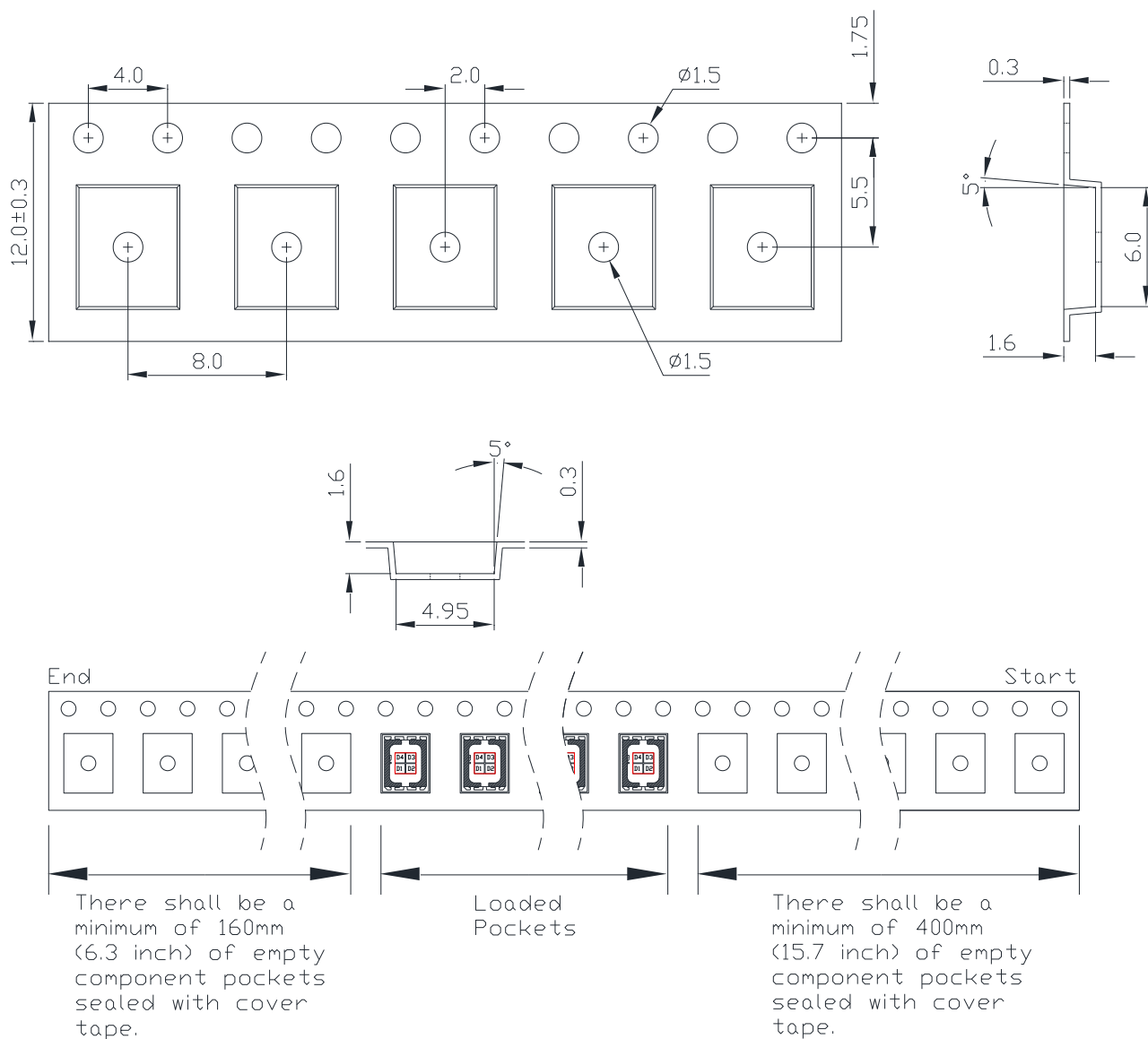
Reflow Soldering Condition

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T_{Smax} to T_p)	3°C / second max.	3°C / second max.
Preheat – Temperature Min (T_{Smin}) – Temperature Max (T_{Smax}) – Time (t_{Smin} to t_{Smax})	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: – Temperature (T_L) – Time (t_l)	183°C 60-150 seconds	217°C 60-150 seconds
Peak/Classification Temperature (T_p)	240°C	260°C
Time Within 5°C of Actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

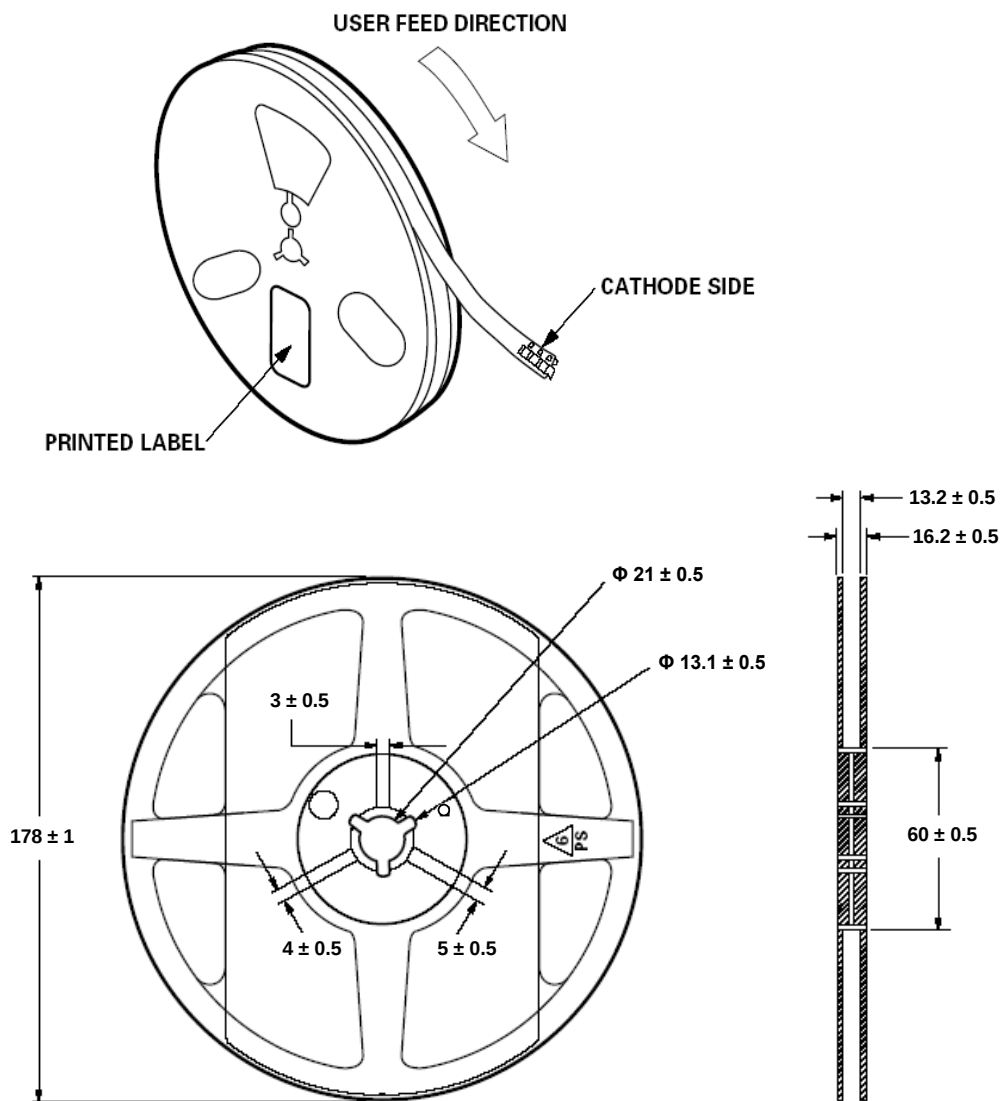
Emitter Reel Packaging



Notes:

1. Drawing not to scale.
2. All dimensions are in millimeters.
3. Unless otherwise indicated, tolerances are ± 0.10 mm.

Emitter Reel Packaging



Notes:

1. Empty component pockets sealed with top cover tape.
2. 250 or 500 pieces per reel.
3. Drawing not to scale.
4. All dimensions are in millimeters.

Precaution for Use

- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue > 47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decided after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets.
<http://www.prolightopto.com/>

Handling of Lens LEDs

Notes for handling of lens LEDs

- Please do not use a force of over 1kgf impact or pressure on the lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- Please do not mold over the lens with another resin. (epoxy, urethane, etc)

